

△ BO 02~12P DIM.A±0.30 ; DIM.B±0.35
13~20P DIM.A±0.35 ; DIM.B±0.35

| PIN | DIM.A | DIM.B | PIN | DIM.A | DIM.B |
|-----|-------|-------|-----|-------|-------|
| 02 | 3.96 | 7.92 | 12 | 43.56 | 47.52 |
| 03 | 7.92 | 11.88 | 13 | 47.52 | 51.48 |
| 04 | 11.88 | 15.84 | 14 | 51.48 | 55.44 |
| 05 | 15.84 | 19.80 | 15 | 55.44 | 59.40 |
| 06 | 19.80 | 23.76 | 16 | 59.40 | 63.36 |
| 07 | 23.76 | 27.72 | 17 | 63.36 | 67.32 |
| 08 | 27.72 | 31.68 | 18 | 67.32 | 71.28 |
| 09 | 31.68 | 35.64 | 19 | 71.28 | 75.24 |
| 10 | 35.64 | 39.60 | 20 | 75.24 | 79.20 |
| 11 | 39.60 | 43.56 | | | |

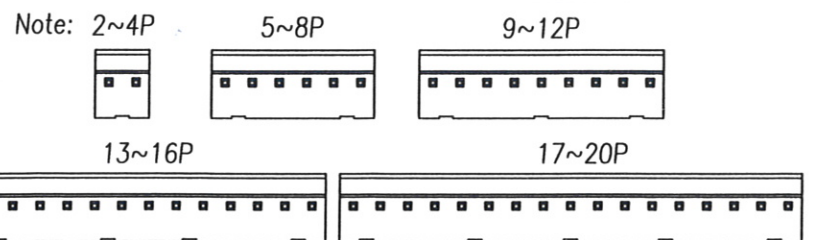
| REV | MODIFICATION | DATE | DRAW |
|-----|------------------------|------------|----------|
| A4 | Release To ECN20130208 | 2013.02.27 | Seven |
| A5 | Release To ECN20131003 | 2013.10.09 | Michelle |
| B0 | Release To ECN20131013 | 2013.10.31 | Michelle |

RoHS Compliant

Specification
 1.Current Rating:7A
 2.Voltage Rating:250V AC/DC
 3.Contact Resistance:10mΩ Max.
 4.Insulation Resistance:1000MΩ Min. At DC 500V
 5.Dielectric Withstanding Voltage:1500 VAC/Minute
 6.Operating Temperature:-25°C~+85°C

Material:
 1.Housing:Thermoplastic UL94V-2
 2.Contact Pin:Copper Alloy SQ. Pin 1.14mm
 Finish:
 1.Housing:Natural
 2.Contact Pin:Bright Tin Plated Over Nickel.
 Part No.: AD02100 XX 0 1 5 2

Number of Pin 02~20 Packing 5:Bag
 Housing Material 0:NY66 UL94V-2 Natural Plating 1:Bright Tin Plated Over Ni



發行
102.11.04
文管中心

金上達科技股份有限公司
GOLDENSUNDA TECHNOLOGY CO.,LTD

| | | | |
|--------------------------------------|-------------------------|---|---|
| TOLERANCE UNLESS OTHERWISE SPECIFIED | PROJ. | TITLE: Wire To Board Wafer 3.96mm 180° DIP Single Row | |
| .X± 0.35 X: ± 2' | APR. Jefferson 20131031 | PART NO. AD02100XX0152 | DWG NO. AD02100XX0152 |
| .XX± 0.25 .X: ± 1' | CHK. Abel 20131031 | UNITS: mm CUSTOMER DRAWING | |
| .XXX± 0.15 .XX: ± 0.5' | DRAW. Michelle 20131031 | SIZE: A4 | SCALE 2.5:1 SHEET 1 / 1 REV B0 V |